

Description

The DI150N03PQ uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 30V I_{D} = 150A$

 $R_{DS(ON)}$ < 2.4m Ω V_{GS}=10V

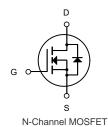
Application

Battery protection

Load switch

Uninterruptible power supply

DFN5X6-8L (TDSON-8-EP(5x6))



Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DI150N03PQ	DFN5X6-8L (TDSON-8-EP(5x6))	HXY MOSFET	5000

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
Vos	Drain-Source Voltage	30		
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	150	Α	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	80	Α	
Ідм	Pulsed Drain Current ²	160	Α	
EAS	Single Pulse Avalanche Energy ³	180	mJ	
las	Avalanche Current	60	Α	
P _D @T _C =25°C	Total Power Dissipation ⁴ 187		W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55		°C	
Reja	Thermal Resistance Junction-Ambient ¹ 62		°C/W	
Rejc	Thermal Resistance Junction-Case ¹	1.1	°C/W	



Electrical Characteristics (T_J =25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
△BV _{DSS} /△T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.014		V/°C	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =30A		2	2.4	0	
	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =15A		2.5	3.2	mΩ	
V _{GS(th)}	Gate Threshold Voltage		1.2		2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	−V _{GS} =V _{DS} , I _D =250uA		-4		mV/°C	
	Dunin Course Lookens Courset	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	uA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5		
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		50		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7		Ω	
Qg	Total Gate Charge (4.5V)			56.9		nC	
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =10V , I _D =15A		13.8			
Q _{gd}	Gate-Drain Charge			23.5			
T _{d(on)}	Turn-On Delay Time			20.1			
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω ,		6.3		ns	
T _{d(off)}	Turn-Off Delay Time	I _D =1A		124.6			
Tf	Fall Time			15.8			
Ciss	Input Capacitance			4345			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		340		pF	
Crss	Reverse Transfer Capacitance			225		1	
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			150	Α	
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =60A
- 4.The power dissipation is limited by 150 $^{\circ}\text{C}$ junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.
- 6.Package limitation current is 85A.



Typical Characteristics

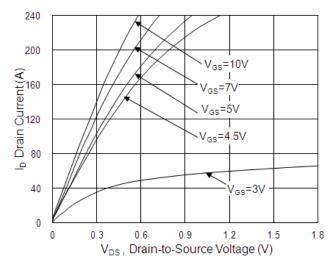


Fig.1 Typical Output Characteristics

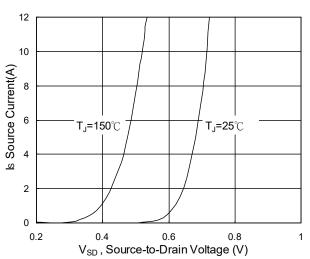


Fig.3 Forward Characteristics of Reverse

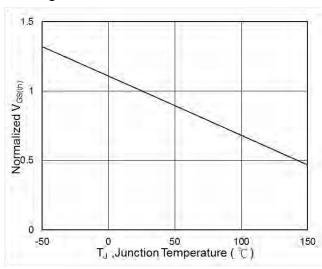


Fig.5 Normalized $V_{\text{GS(th)}}$ v.s T_{J}

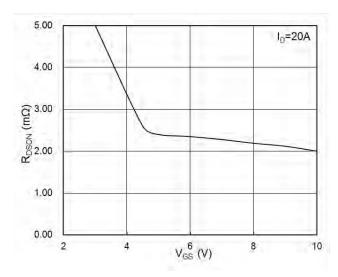


Fig.2 On-Resistance v.s Gate-Source

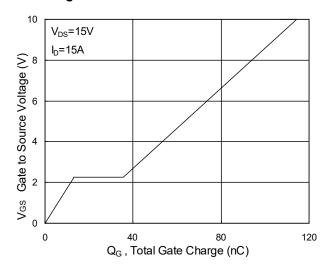


Fig.4 Gate-Charge Characteristics

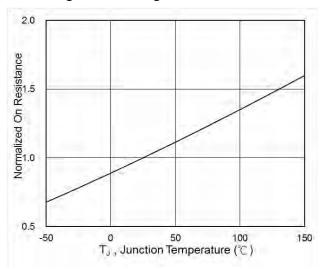
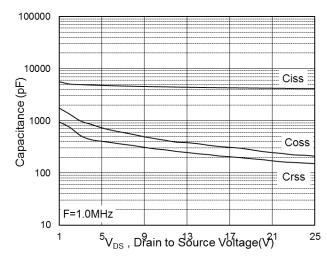


Fig.6 Normalized R_{DSON} v.s T_J





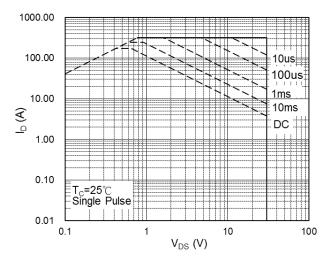


Fig.7 Capacitance

Fig.8 Safe Operating Area

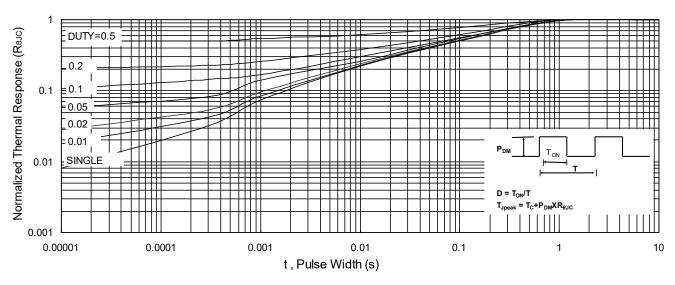


Fig.9 Normalized Maximum Transient Thermal Impedance

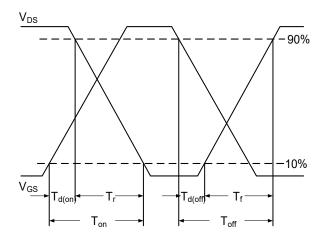


Fig.10 Switching Time Waveform

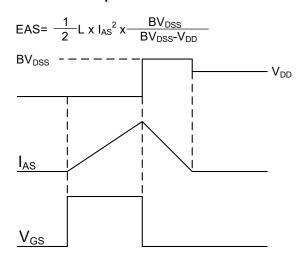
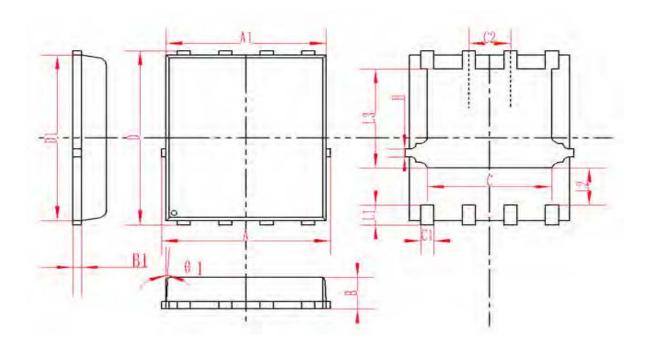


Fig.11 Unclamped Inductive Switching Waveform



DFN5X6-8L(TDSON-8-EP(5x6)) Package Information



SYMBOL	MM		INCH			
	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010



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